

NB7VQ572M

1.8V / 2.5V / 3.3V Differential 4:1 Mux w/Input Equalizer to 1:2 CML Clock/Data Fanout / Translator

Multi-Level Inputs w/ Internal Termination

Description

The NB7VQ572M is a high performance differential 4:1 Clock / Data input multiplexer and a 1:2 CML Clock / Data fanout buffer that operates up to 7 GHz / 10 Gbps respectively with a 1.8 V, 2.5 V, or 3.3 V power supply.

Each IN_x / \overline{IN}_x input pair incorporates a fixed Equalizer Receiver, which when placed in series with a Data path, will enhance the degraded signal transmitted across an FR4 backplane or cable interconnect. For applications that do not require Equalization, consider the NB7V572M, which is pin-compatible to the NB7VQ572M.

The differential Clock / Data inputs have internal 50 Ω termination resistors and will accept differential LVPECL, CML, or LVDS logic levels. The NB7VQ572M incorporates a pair of Select pins that will choose one of four differential inputs and will produce two identical CML output copies of Clock or Data.

As such, the NB7VQ572M is ideal for SONET, GigE, Fiber Channel, Backplane and other Clock/Data distribution applications. The two differential CML outputs will swing 400 mV when externally loaded and terminated with a 50 Ω resistor to V_{CC} and are optimized for low skew and minimal jitter.

The NB7VQ572M is offered in a low profile 5x5 mm 32-pin QFN Pb-Free package. Application notes, models, and support documentation are available at www.onsemi.com. The NB7VQ572M is a member of the GigaComm™ family of high performance clock products.

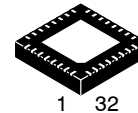
Features

- Input Data Rate > 10 Gb/s Typical
- Data Dependent Jitter < 10 ps
- Maximum Input Clock Frequency > 6 GHz Typical
- Random Clock Jitter < 0.8 ps RMS
- Low Skew 1:2 CML Outputs, < 15 ps max
- 4:1 Multi-Level Mux Inputs, accepts LVPECL, CML, LVDS
- 175 ps Typical Propagation Delay
- 45 ps Typical Rise and Fall Times
- Differential CML Outputs, 400 mV Peak-to-Peak, Typical
- Operating Range: $V_{CC} = 1.71 \text{ V to } 3.6 \text{ V}$ with GND = 0 V
- Internal 50 Ω Input Termination Resistors
- VREFAC Reference Output
- QFN-32 Package, 5mm x 5mm, Pb-Free
- -40°C to +85°C Ambient Operating Temperature
- These are Pb-Free Devices



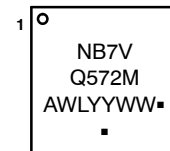
ON Semiconductor®

<http://onsemi.com>



QFN32
MN SUFFIX
CASE 488AM

MARKING DIAGRAM



A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
▪ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information on page 10 of this data sheet.

NB7VQ572M

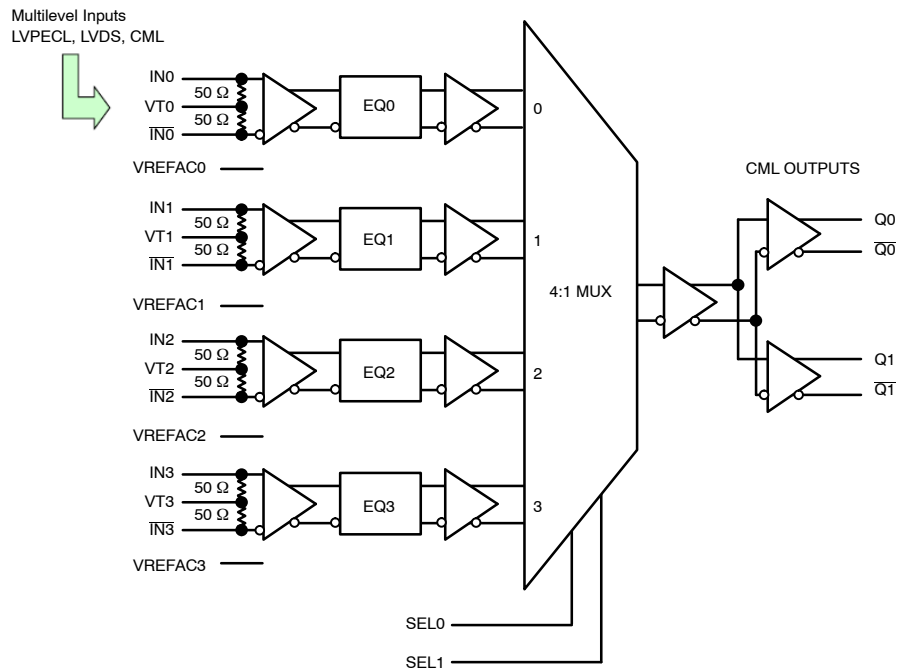


Figure 1. Simplified Block Diagram

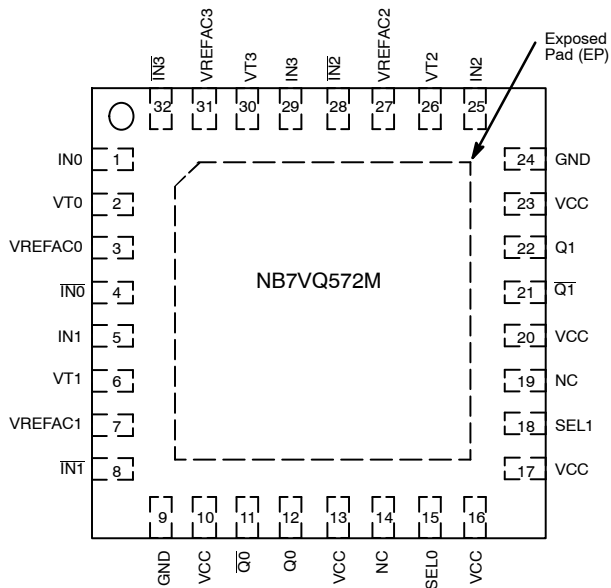


Figure 2. Pinout: QFN-32 (Top View)

Table 1. INPUT SELECT FUNCTION TABLE

SEL1*	SEL0*	Clock / Data Input Selected
0	0	IN0 Input Selected
0	1	IN1 Input Selected
1	0	IN2 Input Selected
1	1	IN3 Input Selected

*Defaults HIGH when left open.

NB7VQ572M

Table 2. PIN DESCRIPTION

Pin Number	Pin Name	I/O	Pin Description
1, 4 5, 8 25, 28 29, 32	IN0, $\overline{IN0}$ IN1, $\overline{IN1}$ IN2, $\overline{IN2}$ IN3, $\overline{IN3}$	LVPECL, CML, LVDS Input	Noninverted, Inverted, Differential Clock or Data Inputs
2, 6 26, 30	VT0, VT1 VT2, VT3		Internal 100 Ω Center-tapped Termination Pin for INx / \overline{INx}
15 18	SEL0 SEL1	LVTTL/LVCMOS Input	Input Select pins, default HIGH when left open through a 94 k Ω pullup resistor. Input logic threshold is $V_{CC}/2$. See Select Function, Table 1.
14, 19	NC	–	No Connect
10, 13, 16 17, 20, 23	V _{CC}	–	Positive Supply Voltage.
11, 12 21, 22	$\overline{Q0}$, Q0 $\overline{Q1}$, Q1	CML Output	Inverted, Non-inverted Differential Outputs.
9, 24	GND		Negative Supply Voltage
3 7 27 31	VREFAC0 VREFAC1 VREFAC2 VREFAC3	–	Output Voltage Reference for Capacitor-Coupled Inputs
–	EP	–	The Exposed Pad (EP) on the QFN-32 package bottom is thermally connected to the die for improved heat transfer out of package. The exposed pad must be attached to a heat-sinking conduit. The pad is electrically connected to the die, and must be electrically connected to GND.

1. In the differential configuration when the input termination pins (VT0, VT1, VT2, VT3) are connected to a common termination voltage or left open, and if no signal is applied on INx/ \overline{INx} input, then the device will be susceptible to self-oscillation.
2. All V_{CC}, and GND pins must be externally connected to a power supply for proper operation.

NB7VQ572M

Table 3. ATTRIBUTES

Characteristics		Value
ESD Protection	Human Body Model Machine Model	> 2 kV > 200 V
R _{PU} – SELx Input Pullup Resistor		28 kΩ
Moisture Sensitivity (Note 3)	QFN–32	Level 1
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V–0 @ 0.125 in
Transistor Count		252
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test		

3. For additional information, see Application Note AND8003/D.

Table 4. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	Positive Power Supply	GND = 0 V		4.0	V
V _{IN}	Positive Input Voltage	GND = 0 V		–0.5 to V _{CC} +0.5	V
V _{INPP}	Differential Input Voltage I _N – I _N			1.89	V
I _{out}	Output Current Through R _T (50 Ω Resistor)			± 40	mA
I _{IN}	Input current Through RT (50 Ω Resistor)			± 40	mA
I _{VREFAC}	V _{REFAC} Sink or Source Current			± 1.5	mA
T _A	Operating Temperature Range			–40 to +85	°C
T _{stg}	Storage Temperature Range			–65 to +150	°C
θ _{JA}	Thermal Resistance (Junction–to–Ambient) (Note 4)	0 lfpm 500 lfpm	QFN–32 QFN–32	31 27	°C/W °C/W
θ _{JC}	Thermal Resistance (Junction–to–Case) (Note 4)		QFN–32	12	°C/W
T _{sol}	Wave Solder	≤ 20 sec		265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

4. JEDEC standard multilayer board – 2S2P (2 signal, 2 power) with 8 filled thermal vias under exposed pad.

NB7VQ572M

Table 5. DC CHARACTERISTICS CML OUTPUT $V_{CC} = 1.71\text{ V to }3.6\text{ V}$, $GND = 0\text{ V}$, $T_A = -40^\circ\text{C to }+85^\circ\text{C}$ (Note 5)

Symbol	Characteristic	Min	Typ	Max	Unit	
POWER SUPPLY						
V_{CC}	Power Supply Voltage	$V_{CC} = 3.3\text{ V}$	3.0	3.3	3.6	V
		$V_{CC} = 2.5\text{ V}$	2.375	2.5	2.625	
		$V_{CC} = 1.8\text{ V}$	1.71	1.8	1.89	
I_{CC}	Power Supply Current for V_{CC} (Inputs and Outputs Open)	$V_{CC} = 3.3\text{ V}$		130	160	mA
		$V_{CC} = 2.5\text{ V}$		120	145	
		$V_{CC} = 1.8\text{ V}$		100	120	

CML OUTPUTS (Note 6)

V_{OH}	Output HIGH Voltage	$V_{CC} = 3.3\text{ V}$	$V_{CC} - 30$ 3270	$V_{CC} - 5$ 3295	V_{CC} 3300	mV
		$V_{CC} = 2.5\text{ V}$	2470	2495	2500	
		$V_{CC} = 1.8\text{ V}$	1770	1795	1800	
V_{OL}	Output LOW Voltage	$V_{CC} = 3.3\text{ V}$	$V_{CC} - 550$ 2675	$V_{CC} - 450$ 2825	$V_{CC} - 350$ 2975	mV
		$V_{CC} = 2.5\text{ V}$	1875	2025	2175	
		$V_{CC} = 1.8\text{ V}$		1325	1475	
V_{OL}	Output LOW Voltage	$V_{CC} = 3.3\text{ V}$	$V_{CC} - 625$ 2675	$V_{CC} - 475$ 2825	$V_{CC} - 325$ 2975	mV
		$V_{CC} = 2.5\text{ V}$	$V_{CC} - 600$ 1900	$V_{CC} - 475$ 2025	$V_{CC} - 350$ 2150	
		$V_{CC} = 1.8\text{ V}$	$V_{CC} - 550$ 1250	$V_{CC} - 450$ 1350	$V_{CC} - 350$ 1450	

DIFFERENTIAL CLOCK INPUTS DRIVEN SINGLE-ENDED (Figures 7 and 8) (Note 7)

V_{IH}	Single-ended Input HIGH Voltage	$V_{th} + 100$		V_{CC}	mV
V_{IL}	Single-ended Input LOW Voltage	GND		$V_{th} - 100$	mV
V_{th}	Input Threshold Reference Voltage Range (Note 8)	1100		$V_{CC} - 100$	mV
V_{ISE}	Single-ended Input Voltage ($V_{IH} - V_{IL}$)	200		1200	mV

VREFAC

V_{REFAC}	Output Reference Voltage (100 μA Load)	$V_{CC} = 3.3\text{ V}$	$V_{CC} - 800$	$V_{CC} - 625$	$V_{CC} - 500$	mV
		$V_{CC} = 2.5\text{ V}$	$V_{CC} - 750$	$V_{CC} - 575$	$V_{CC} - 450$	
		$V_{CC} = 1.8\text{ V}$	1050	$V_{CC} - 525$	$V_{CC} - 400$	

DIFFERENTIAL INPUTS DRIVEN DIFFERENTIALLY (Figures 9 and 10) (Note 9)

V_{IHD}	Differential Input HIGH Voltage (IN, $\overline{\text{IN}}$)	1200		V_{CC}	mV
V_{ILD}	Differential Input LOW Voltage (IN, $\overline{\text{IN}}$)	0		$V_{IHD} - 100$	mV
V_{ID}	Differential Input Voltage (IN, $\overline{\text{IN}}$) ($V_{IHD} - V_{ILD}$)	100		1200	mV
V_{CMR}	Input Common Mode Range (Differential Configuration, Note 10) (Figure 11)	1150		$V_{CC} - 50$	mV
I_{IH}	Input HIGH Current IN / $\overline{\text{IN}}$ ($V_{TIN}/\overline{V_{TIN}}$ Open)	-150		150	μA
I_{IL}	Input LOW Current IN / $\overline{\text{IN}}$ ($V_{TIN}/\overline{V_{TIN}}$ Open)	-150		150	μA

CONTROL INPUT (SELx Pin)

V_{IH}	Input HIGH Voltage for Control Pin	$V_{CC} \times 0.65$		V_{CC}	V
V_{IL}	Input LOW Voltage for Control Pin	GND		$V_{CC} \times 0.35$	V
I_{IH}	Input HIGH Current	-150		150	μA
I_{IL}	Input LOW Current	-150		150	μA

TERMINATION RESISTORS

R_{TIN}	Internal Input Termination Resistor (Measured from INx to VTx)	45	50	55	Ω
R_{TOUT}	Internal Output Termination Resistor	45	50	55	Ω

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

5. Input and Output parameters vary 1:1 with V_{CC} .
6. CML outputs loaded with 50 Ω to V_{CC} for proper operation.
7. V_{th} , V_{IH} , V_{IL} , and V_{ISE} parameters must be complied with simultaneously.
8. V_{th} is applied to the complementary input when operating in single-ended mode.
9. V_{IHD} , V_{ILD} , V_{ID} and V_{CMR} parameters must be complied with simultaneously.
10. V_{CMR} min varies 1:1 with GND, V_{CMR} max varies 1:1 with V_{CC} . The V_{CMR} range is referenced to the most positive side of the differential input signal.

NB7VQ572M

Table 6. AC CHARACTERISTICS $V_{CC} = 1.71\text{ V to }3.6\text{ V}$, $GND = 0\text{ V}$, $T_A = -40^\circ\text{C to }+85^\circ\text{C}$ (Note 11)

Symbol	Characteristic	Min	Typ	Max	Unit
f_{MAX}	Maximum Input Clock Frequency $V_{OUT} \geq 200\text{ mV}$	6	7		GHz
$f_{DATAMAX}$	Maximum Operating Data Rate NRZ, (PRBS23)	10	11		Gbps
f_{SEL}	Maximum Toggle Frequency, SELx	4	10		MHz
V_{OUTPP}	Output Voltage Amplitude (@ $V_{INPPmin}$) (Note 12) (Figure 12) $f_{in} \leq 5\text{ GHz}$	250	400		mV
t_{PLH} , t_{PHL}	Propagation Delay to Differential Outputs Measured at Differential Crosspoint @ 1 GHz INx/INx to Qx/Qx @ 50 MHz SELx to Qx	100	175 7	250 20	ps ns
$t_{PD\ Tempco}$	Differential Propagation Delay Temperature Coefficient		50		$\Delta fs/^\circ C$
t_{skew}	Output – Output skew (within device) (Note 13) Device – Device skew ($t_{pdmax} - t_{pdmin}$)		0 30	15 100	ps
t_{DC}	Output Clock Duty Cycle (Reference Duty Cycle = 50%) $f_{in} \leq 5\text{ GHz}$	45	50	55	%
Φ_N	Phase Noise, $f_{in} = 1\text{ GHz}$ 10 kHz 100 kHz 1 MHz 10 MHz 20 MHz 40 MHz		-134 -136 -149 -149 -149 -149		dBc
$t_{J\Phi N}$	Integrated Phase Jitter (Figure TBD) $f_{in} = 1\text{ GHz}$, 12 kHz – 20 MHz Offset (RMS)		35		fs
t_{JITTER}	Random Clock Jitter, RJ (Note 14) Deterministic Jitter, DJ (Note 15) $f_{in} \leq 6\text{ GHz}$		0.2	0.8	ps RMS
	$f_{in} \leq 10\text{ Gbps}$ (12" FR4) Crosstalk Induced Jitter (Adjacent Channel) (Note 17)			10 0.7	ps pk-pk ps RMS
V_{INPP}	Input Voltage Swing (Differential Configuration) (Note 16)	100		1200	mV
t_r , t_f	Output Rise/Falltimes @ 1 GHz; (20% – 80%), $V_{IN} = 400\text{ mV}$ Qx, Qx	25	45	65	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

11. Measured using a 150 mVpk-pk source, 50% duty cycle clock source. All output loading with external 50 Ω to V_{CC} . Input edge rates 40 ps (20% – 80%).
12. Output voltage swing is a single-ended measurement operating in differential mode.
13. Skew is measured between outputs under identical transitions and conditions. Duty cycle skew is defined only for differential operation when the delays are measured from crosspoint of the inputs to the crosspoint of the outputs.
14. Additive RMS jitter with 50% duty cycle clock signal.
15. Additive Peak-to-Peak data dependent jitter with input NRZ data at PRBS23.
16. Input voltage swing is a single-ended measurement operating in differential mode.
17. Crosstalk is measured at the output while applying two similar clock frequencies that are asynchronous with respect to each other at the inputs.

NB7VQ572M

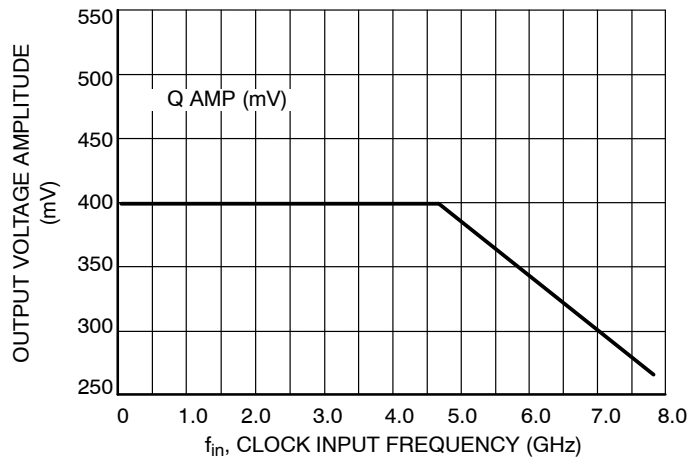


Figure 3. Clock Output Voltage Amplitude (V_{OUTPP}) vs. Input Frequency (f_{in}) at Ambient Temperature (Typical)

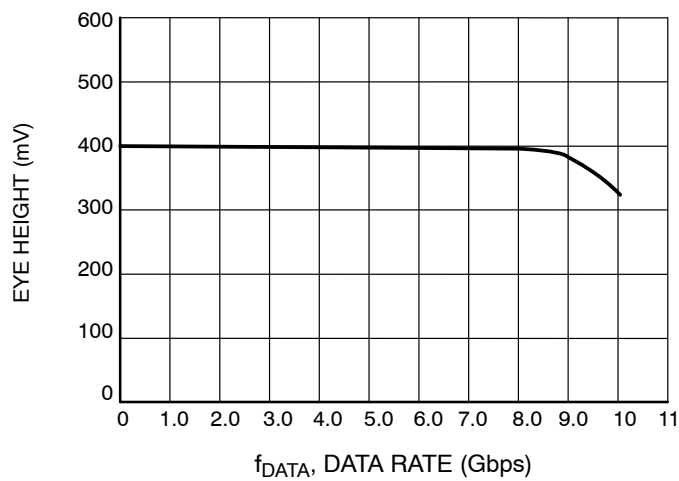


Figure 4. Inside Eye Height vs. Input Data Rate (Gbps) at Ambient Temperature (typical), FR4 = 12"

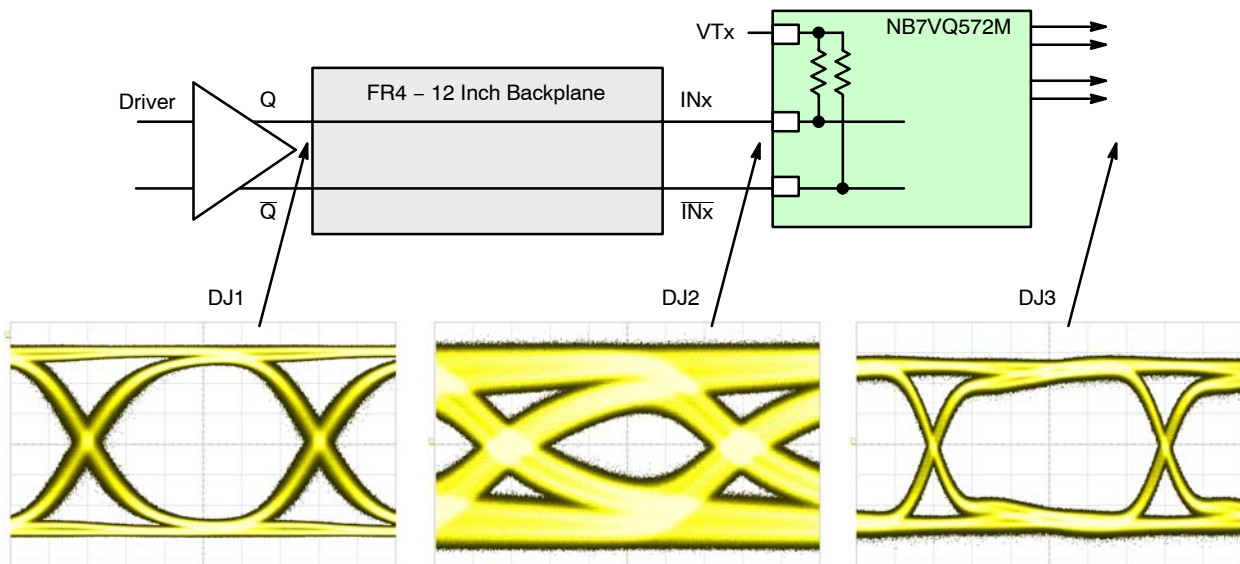


Figure 5. Typical NB7VQ572M Equalizer Application and Interconnect with PRBS23 Pattern at 10 Gbps

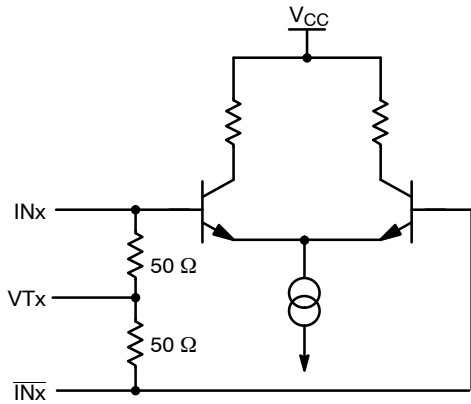


Figure 6. Input Structure

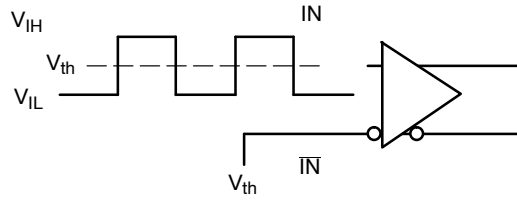


Figure 7. Differential Input Driven Single-Ended

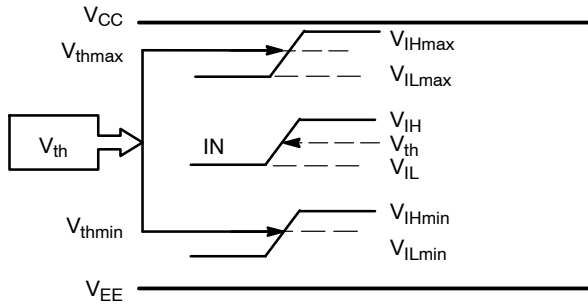


Figure 8. V_{th} Diagram

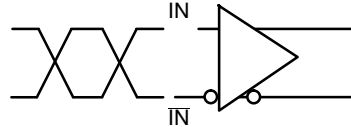


Figure 9. Differential Inputs Driven Differentially

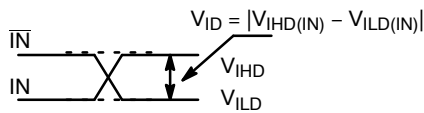


Figure 10. Differential Inputs Driven Differentially

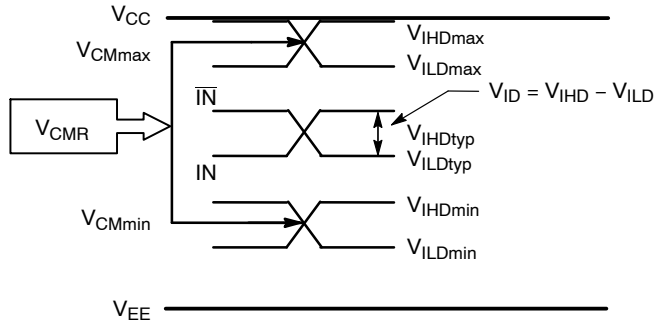


Figure 11. V_{CMR} Diagram

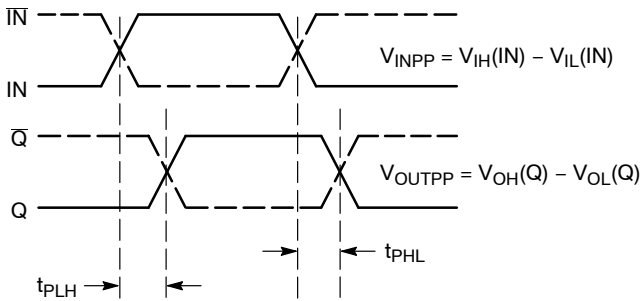


Figure 12. AC Reference Measurement

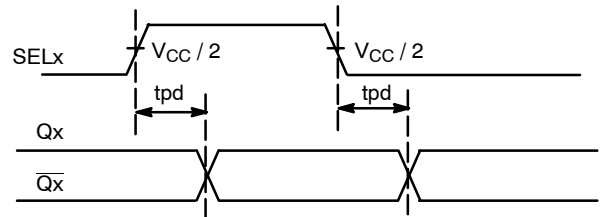


Figure 13. SEL_x to Q_x Timing Diagram

NB7VQ572M

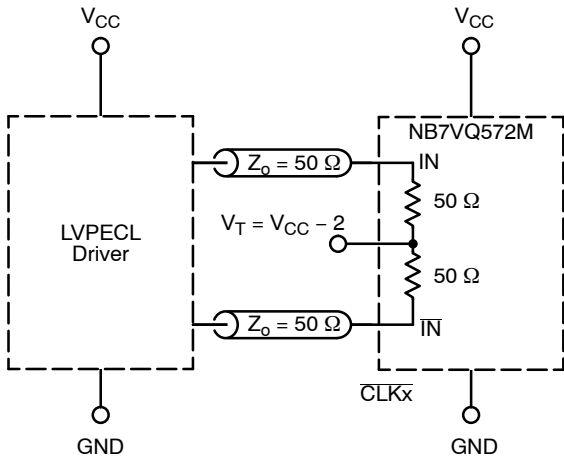


Figure 14. LVPECL Interface

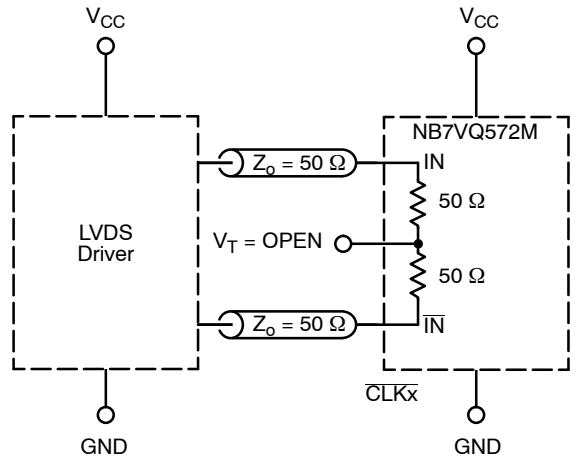


Figure 15. LVDS Interface

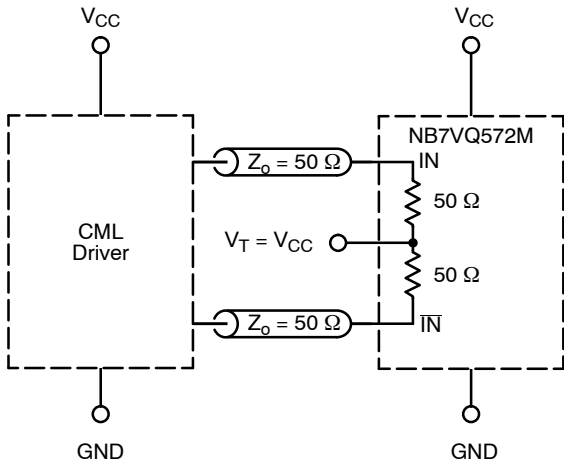


Figure 16. Standard 50 Ω Load CML Interface

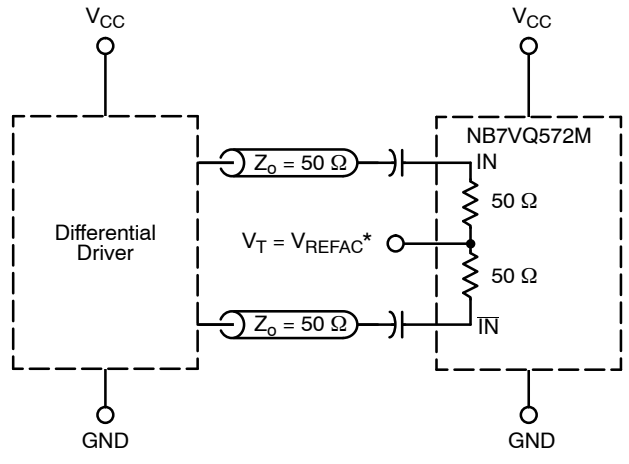


Figure 17. Capacitor-Coupled Differential Interface (V_T Connected to V_{REFAC})

* V_{REFAC} bypassed to ground with a 0.01 μF capacitor.

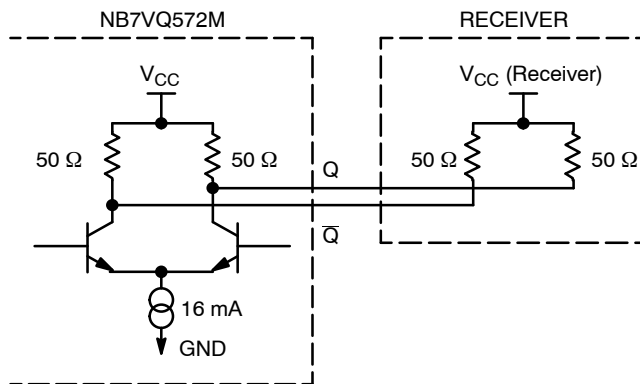


Figure 18. Typical CML Output Structure and Termination

NB7VQ572M

DEVICE ORDERING INFORMATION

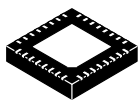
Device	Package	Shipping†
NB7VQ572MMNG	QFN-32 (Pb-free)	74 Units / Rail
NB7VQ572MMNR4G	QFN-32 (Pb-free)	1000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

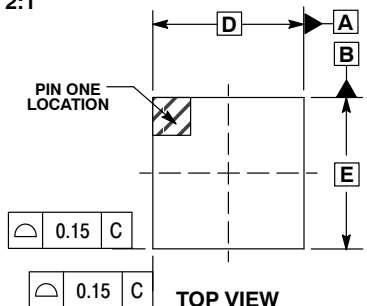


1 32

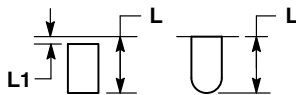
SCALE 2:1

QFN32 5x5, 0.5P
CASE 488AM
ISSUE A

DATE 23 OCT 2013



TOP VIEW

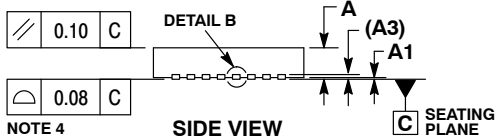


DETAIL A
ALTERNATE TERMINAL
CONSTRUCTIONS

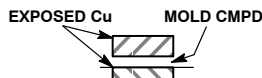
NOTES:

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30MM FROM THE TERMINAL TIP. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.80	1.00
A1	---	0.05
A3	0.20	REF
b	0.18	0.30
D	5.00	BSC
D2	2.95	3.25
E	5.00	BSC
E2	2.95	3.25
e	0.50	BSC
K	0.20	---
L	0.30	0.50
L1	---	0.15

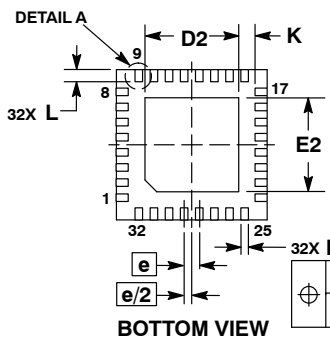


SIDE VIEW



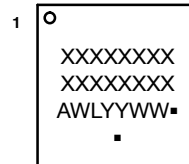
DETAIL B
ALTERNATE
CONSTRUCTION

GENERIC
MARKING DIAGRAM*



BOTTOM VIEW

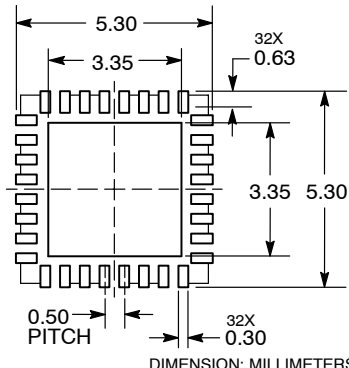
⊕	0.10 (M)	C	A	B
	0.05 (M)	C	NOTE 3	



- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)
*This information is generic. Please refer to device data sheet for actual part marking.
Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED
SOLDERING FOOTPRINT*



DIMENSION: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON20032D	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	QFN32 5x5 0.5P	PAGE 1 OF 1

ON Semiconductor and ON are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

TECHNICAL SUPPORT

North American Technical Support:

Voice Mail: 1 800-282-9855 Toll Free USA/Canada

Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative